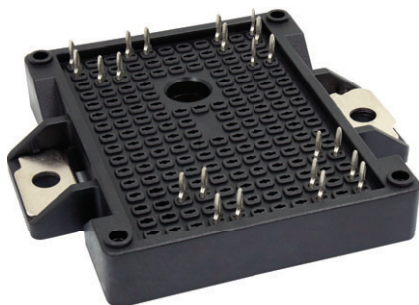


EMIPAK-2B PressFit Power Module

3-Levels Half-Bridge Inverter Stage, 150 A



EMIPAK-2B
(package example)



RoHS
COMPLIANT

FEATURES

- Trench IGBT technology
- FRED Pt® clamping diodes
- PressFit pins technology
- Exposed Al₂O₃ substrate with low thermal resistance
- Short circuit rated
- Square RBSOA
- Integrated thermistor
- Low internal inductances
- Low switching loss
- UL approved file E78996 
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION

VS-ETF150Y65U is an integrated solution for a multi level inverter stage in a single package. The EMIPAK-2B package is easy to use thanks to the PressFit pins and the exposed substrate provides improved thermal performance. The optimized layout also helps to minimize stray parameters, allowing for better EMI performance.

PRODUCT SUMMARY	
Q1 - Q4 IGBT STAGE	
V _{CES}	650 V
V _{CE(ON)} typical at I _C = 100 A	1.72 V
Q2 - Q3 IGBT STAGE	
V _{CES}	650 V
V _{CE(ON)} typical at I _C = 150 A	1.75 V
I _C at T _C = 82 °C	150 A
Speed	8 kHz to 30 kHz
Package	EMIPAK-2B
Circuit	3-levels half bridge inverter stage

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Operating junction temperature	T _J		175	°C
Storage temperature range	T _{Stg}		-40 to +150	
RMS isolation voltage	V _{ISOL}	T _J = 25 °C, all terminals shorted, f = 50 Hz, t = 1 s	3500	V
Q1 - Q4 IGBT				
Collector to emitter voltage	V _{CES}		650	V
Gate to emitter voltage	V _{GES}		20	
Pulsed collector current	I _{CM}		220	A
Clamped inductive load current	I _{LM} ⁽¹⁾		220	
Continuous collector current	I _C	T _C = 25 °C	142	A
		T _C = 60 °C	121	
		T _{SINK} = 60 °C	64	
Power dissipation	P _D	T _C = 25 °C	417	W
		T _C = 60 °C	319	
Q2 - Q3 IGBT				
Collector to emitter voltage	V _{CES}		650	V
Gate to emitter voltage	V _{GES}		20	
Pulsed collector current	I _{CM}		300	A
Clamped inductive load current	I _{LM} ⁽¹⁾		300	
Continuous collector current	I _C	T _C = 25 °C	201	A
		T _C = 60 °C	171	
		T _{SINK} = 60 °C	77	
Power dissipation	P _D	T _C = 25 °C	600	W
		T _C = 60 °C	460	

**ABSOLUTE MAXIMUM RATINGS**

PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
D5 - D6 CLAMPING DIODE				
Repetitive peak reverse voltage	V _{RRM}		650	V
Single pulse forward current	I _{FSM}	10 ms sine or 6 ms rectangular pulse, T _J = 25 °C	380	A
Diode continuous forward current	I _F	T _C = 25 °C	95	
		T _C = 60 °C	80	
		T _{SINK} = 60 °C	45	
Power dissipation	P _D	T _C = 25 °C	221	W
		T _C = 60 °C	169	
D1 - D2 - D3 - D4 AP DIODE				
Single pulse forward current	I _{FSM}	10 ms sine or 6 ms rectangular pulse, T _J = 25 °C	250	A
Diode continuous forward current	I _F	T _C = 25 °C	78	
		T _C = 60 °C	66	
		T _{SINK} = 60 °C	43	
Power dissipation	P _D	T _C = 25 °C	176	W
		T _C = 60 °C	135	

Notes

- Absolute Maximum Ratings indicate sustained limits beyond which damage to the device may occur.
- (1) $V_{CC} = 325\text{ V}$, $V_{GE} = 15\text{ V}$, $L = 500\text{ }\mu\text{H}$, $R_g = 4.7\text{ }\Omega$, $T_J = 175\text{ }^{\circ}\text{C}$

ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Q1 - Q4 IGBT						
Collector to emitter breakdown voltage	BV _{CES}	V _{GE} = 0 V, I _C = 100 μA	650	-	-	V
Collector to emitter voltage	V _{CE(ON)}	V _{GE} = 15 V, I _C = 100 A	-	1.72	2.06	
		V _{GE} = 15 V, I _C = 100 A, T _J = 125 °C	-	1.94	-	
Gate threshold voltage	V _{GE(th)}	V _{CE} = V _{GE} , I _C = 3.3 mA	5.0	6.3	8.4	
Temperature coefficient of threshold voltage	ΔV _{GE(th)} /ΔT _J	V _{CE} = V _{GE} , I _C = 1 mA (25 °C to 125 °C)	-	-19	-	mV/°C
Forward transconductance	g _{fe}	V _{CE} = 20 V, I _C = 100 A	-	71	-	S
Transfer characteristics	V _{GE}	V _{CE} = 20 V, I _C = 100 A	-	10.5	-	V
Zero gate voltage collector current	I _{CES}	V _{GE} = 0 V, V _{CE} = 650 V	-	0.2	100	μA
		V _{GE} = 0 V, V _{CE} = 650 V, T _J = 125 °C	-	60	-	
Gate to emitter leakage current	I _{GES}	V _{GE} = ± 20 V, V _{CE} = 0 V	-	-	± 600	nA
Q2 - Q3 IGBT						
Collector to emitter breakdown voltage	BV _{CES}	V _{GE} = 0 V, I _C = 100 μA	650	-	-	V
Collector to emitter voltage	V _{CE(ON)}	V _{GE} = 15 V, I _C = 150 A	-	1.75	2.17	
		V _{GE} = 15 V, I _C = 150 A, T _J = 125 °C	-	1.99	-	
Gate threshold voltage	V _{GE(th)}	V _{CE} = V _{GE} , I _C = 5.0 mA	5.0	5.9	8.4	
Temperature coefficient of threshold voltage	ΔV _{GE(th)} /ΔT _J	V _{CE} = V _{GE} , I _C = 1.0 mA (25 °C to 125 °C)	-	-19	-	mV/°C
Forward transconductance	g _{fe}	V _{CE} = 20 V, I _C = 150 A	-	102	-	S
Transfer characteristics	V _{GE}	V _{CE} = 20 V, I _C = 150 A	-	9.8	-	V
Zero gate voltage collector current	I _{CES}	V _{GE} = 0 V, V _{CE} = 650 V	-	0.2	100	μA
		V _{GE} = 0 V, V _{CE} = 650 V, T _J = 125 °C	-	100	-	
Gate to emitter leakage current	I _{GES}	V _{GE} = ± 20 V, V _{CE} = 0 V	-	-	± 600	nA
D5 - D6 CLAMPING DIODE						
Cathode to anode blocking voltage	V _{BR}	I _R = 100 μA	650	-	-	V
Forward voltage drop	V _{FM}	I _F = 100 A	-	2.3	3.15	
		I _F = 100 A, T _J = 125 °C	-	1.6	-	
Reverse leakage current	I _{RM}	V _R = 650 V	-	0.2	75	μA
		V _R = 650 V, T _J = 125 °C	-	110	-	
D1 - D2 - D3 - D4 AP DIODE						
Forward voltage drop	V _{FM}	I _F = 100 A	-	2.14	3.18	V
		I _F = 100 A, T _J = 125 °C	-	1.79	-	



SWITCHING CHARACTERISTICS ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Q1 - Q4 IGBT (WITH D5 - D6 CLAMPING DIODE)						
Total gate charge (turn-on)	Q_g	$I_C = 100\text{ A}$ $V_{CC} = 400\text{ V}$ $V_{GE} = 15\text{ V}$	-	190	-	nC
Gate to emitter charge (turn-on)	Q_{ge}		-	65	-	
Gate to collector charge (turn-on)	Q_{gc}		-	80	-	
Turn-on switching loss	E_{ON}	$I_C = 100\text{ A}$ $V_{CC} = 325\text{ V}$ $V_{GE} = 15\text{ V}$ $R_g = 4.7\text{ }\Omega$ $L = 500\text{ }\mu\text{H}^{(1)}$	-	0.43	-	mJ
Turn-off switching loss	E_{OFF}		-	1.04	-	
Total switching loss	E_{TOT}		-	1.47	-	
Turn-on delay time	$t_{d(on)}$		-	113	-	ns
Rise time	t_r		-	50	-	
Turn-off delay time	$t_{d(off)}$		-	108	-	
Fall time	t_f	$I_C = 100\text{ A}$ $V_{CC} = 325\text{ V}$ $V_{GE} = 15\text{ V}$ $R_g = 4.7\text{ }\Omega$ $L = 500\text{ }\mu\text{H}$ $T_J = 125\text{ }^{\circ}\text{C}^{(1)}$	-	57	-	mJ
Turn-on switching loss	E_{ON}		-	0.61	-	
Turn-off switching loss	E_{OFF}		-	1.49	-	
Total switching loss	E_{TOT}		-	2.1	-	ns
Turn-on delay time	$t_{d(on)}$		-	113	-	
Rise time	t_r		-	51	-	
Turn-off delay time	$t_{d(off)}$	$V_{GE} = 0\text{ V}$ $V_{CC} = 30\text{ V}$ $f = 1\text{ MHz}$	-	117	-	pF
Fall time	t_f		-	79	-	
Input capacitance	C_{ies}		-	6600	-	
Output capacitance	C_{oes}	$T_J = 175\text{ }^{\circ}\text{C}$, $I_C = 220\text{ A}$ $V_{CC} = 325\text{ V}$, $V_P = 650\text{ V}$ $R_g = 4.7\text{ }\Omega$, $V_{GE} = 15\text{ V to }0\text{ V}$	-	340	-	pF
Reverse transfer capacitance	C_{res}		-	180	-	
Reverse bias safe operating area	RBSOA		Fullsquare			
Short circuit safe operating area	SCSOA	$R_g = 5.0\text{ }\Omega$, $V_{CC} = 400\text{ V}$, $V_P = 600\text{ V}$ $V_{GE} = 15\text{ V to }0$, $T_J = 150\text{ }^{\circ}\text{C}$	-	-	5.5	μs
Q2 - Q3 IGBT (WITH D2 - D3 AP DIODE)						
Total gate charge (turn-on)	Q_g	$I_C = 150\text{ A}$ $V_{CC} = 400\text{ V}$ $V_{GE} = 15\text{ V}$	-	310	-	nC
Gate to emitter charge (turn-on)	Q_{ge}		-	95	-	
Gate to collector charge (turn-on)	Q_{gc}		-	130	-	
Turn-on switching loss	E_{ON}	$I_C = 150\text{ A}$ $V_{CC} = 325\text{ V}$ $V_{GE} = 15\text{ V}$ $R_g = 4.7\text{ }\Omega$ $L = 500\text{ }\mu\text{H}^{(1)}$	-	0.49	-	mJ
Turn-off switching loss	E_{OFF}		-	2.51	-	
Total switching loss	E_{TOT}		-	3.0	-	
Turn-on delay time	$t_{d(on)}$		-	162	-	ns
Rise time	t_r		-	71	-	
Turn-off delay time	$t_{d(off)}$		-	148	-	
Fall time	t_f	$I_C = 150\text{ A}$ $V_{CC} = 325\text{ V}$ $V_{GE} = 15\text{ V}$ $R_g = 4.7\text{ }\Omega$ $L = 500\text{ }\mu\text{H}$ $T_J = 125\text{ }^{\circ}\text{C}^{(1)}$	-	64	-	mJ
Turn-on switching loss	E_{ON}		-	0.62	-	
Turn-off switching loss	E_{OFF}		-	3.18	-	
Total switching loss	E_{TOT}		-	3.8	-	ns
Turn-on delay time	$t_{d(on)}$		-	162	-	
Rise time	t_r		-	75	-	
Turn-off delay time	$t_{d(off)}$	$V_{GE} = 0\text{ V}$ $V_{CC} = 30\text{ V}$ $f = 1\text{ MHz}$	-	153	-	pF
Fall time	t_f		-	81	-	
Input capacitance	C_{ies}		-	9900	-	
Output capacitance	C_{oes}	$T_J = 175\text{ }^{\circ}\text{C}$, $I_C = 300\text{ A}$ $V_{CC} = 325\text{ V}$, $V_P = 650\text{ V}$ $R_g = 4.7\text{ }\Omega$, $V_{GE} = 15\text{ V to }0\text{ V}$	-	460	-	pF
Reverse transfer capacitance	C_{res}		-	250	-	
Reverse bias safe operating area	RBSOA		Fullsquare			
Short circuit safe operating area	SCSOA	$R_g = 5.0\text{ }\Omega$, $V_{CC} = 400\text{ V}$, $V_P = 600\text{ V}$ $V_{GE} = 15\text{ V to }0$, $T_J = 150\text{ }^{\circ}\text{C}$	-	-	5.5	μs



SWITCHING CHARACTERISTICS (T _J = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
D5 - D6 CLAMPING DIODE						
Diode reverse recovery time	t _{rr}	V _R = 200 V I _F = 50 A di/dt = 500 A/μs	-	55	-	ns
Diode peak reverse current	I _{rr}		-	8.7	-	A
Diode recovery charge	Q _{rr}		-	242	-	nC
Diode reverse recovery time	t _{rr}	V _R = 200 V I _F = 50 A di/dt = 500 A/μs, T _J = 125 °C	-	112	-	ns
Diode peak reverse current	I _{rr}		-	21	-	A
Diode recovery charge	Q _{rr}		-	1177	-	nC
D1 - D2 - D3 - D4 AP DIODE						
Diode reverse recovery time	t _{rr}	V _R = 200 V I _F = 50 A di/dt = 500 A/μs	-	66	-	ns
Diode peak reverse current	I _{rr}		-	11	-	A
Diode recovery charge	Q _{rr}		-	363	-	nC
Diode reverse recovery time	t _{rr}	V _R = 200 V I _F = 50 A di/dt = 500 A/μs, T _J = 125 °C	-	130	-	ns
Diode peak reverse current	I _{rr}		-	21.3	-	A
Diode recovery charge	Q _{rr}		-	1392	-	nC

Note

(1) Energy losses include "tail" and diode reverse recovery.

INTERNAL NTC - THERMISTOR SPECIFICATIONS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUE	UNITS
Resistance	R_{25}	$T_C = 25\text{ }^{\circ}\text{C}$	5000	Ω
	R_{100}	$T_C = 100\text{ }^{\circ}\text{C}$	$493 \pm 5\%$	
B-value	$B_{25/50}$	$R_2 = R_{25} \exp. [B_{25/50} (1/T_2 - 1/(298.15\text{ K}))]$	$3375 \pm 5\%$	K
Maximum operating temperature			220	$^{\circ}\text{C}$
Dissipation constant			2	$\text{mW}/^{\circ}\text{C}$
Thermal time constant			8	s

THERMAL AND MECHANICAL SPECIFICATIONS					
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNITS
Q1 - Q4 IGBT - Junction to case thermal resistance (per switch)	R_{thJC}	-	-	0.36	$^{\circ}\text{C}/\text{W}$
Q2 - Q3 IGBT - Junction to case thermal resistance (per switch)		-	-	0.25	
D5 - D6 Clamping diode - Junction to case thermal resistance (per diode)		-	-	0.68	
D1 - D2 - D3 - D4 AP diode - Junction to case thermal resistance (per diode)		-	-	0.85	
Q1 - Q4 IGBT - Case to sink thermal resistance (per switch)	$R_{thCS}^{(1)}$	-	0.63	-	
Q2 - Q3 IGBT - Case to sink thermal resistance (per switch)		-	0.62	-	
D5 - D6 Clamping diode - Case to sink thermal resistance (per diode)		-	1.0	-	
D1 - D2 - D3 - D4 AP diode - Case to sink thermal resistance (per diode)		-	0.78	-	
Case to sink thermal resistance per module		-	0.08	-	$^{\circ}\text{C}/\text{W}$
Mounting torque (M4)		2	-	3	Nm
Weight		-	45	-	g

Note

(1) Mounting surface flat, smooth, and greased

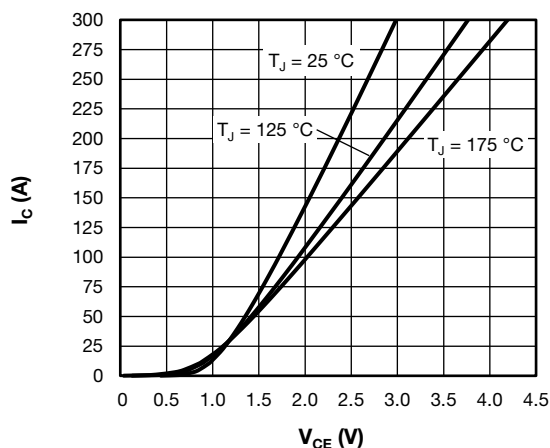


Fig. 1 - I_C vs. V_{CE} ,
Typical Q1 - Q4 Trench IGBT Output Characteristics, $V_{GE} = 15$ V

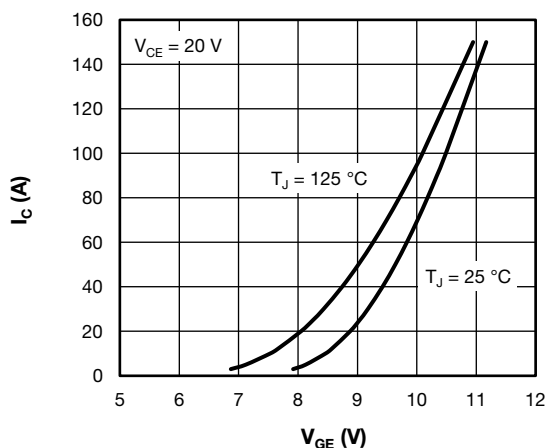


Fig. 4 - I_C vs V_{GE}
Typical Q1 - Q4 Trench IGBT Transfer Characteristics

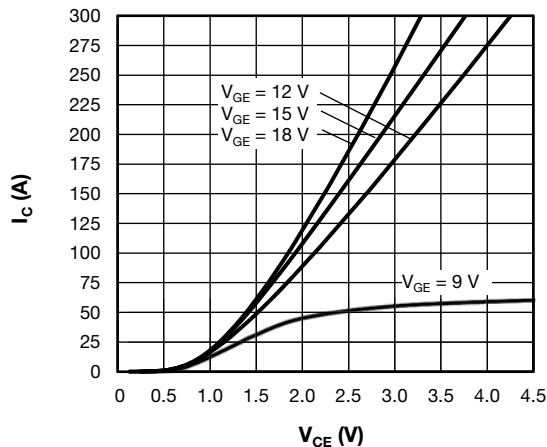


Fig. 2 - I_C vs. V_{CE}
Typical Q1 - Q4 Trench IGBT Output Characteristics, $T_J = 125$ °C

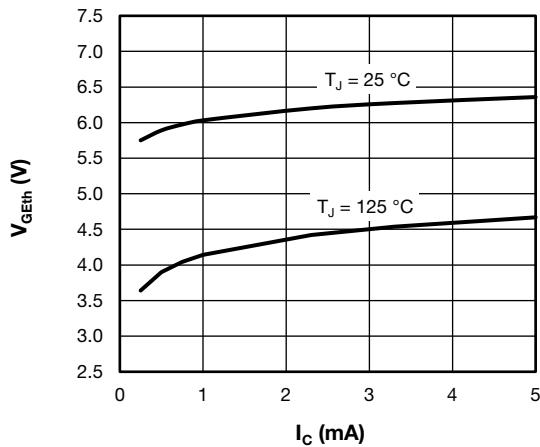


Fig. 5 - V_{GEth} vs. I_C
Typical Q1 - Q4 Trench IGBT Gate Threshold Voltage

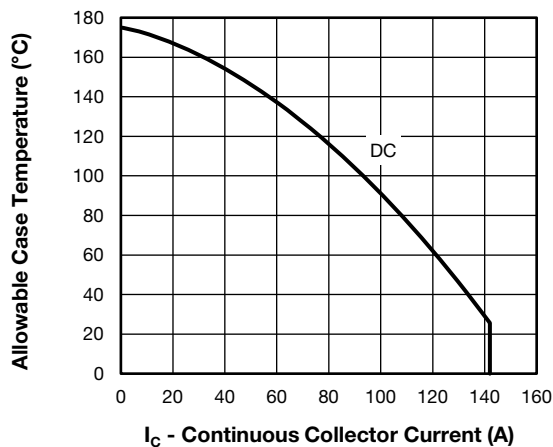


Fig. 3 - Allowable Case Temperature vs. Continuous Collector Current,
Maximum Q1 - Q4 IGBT Continuous Collector Current vs.
Case Temperature

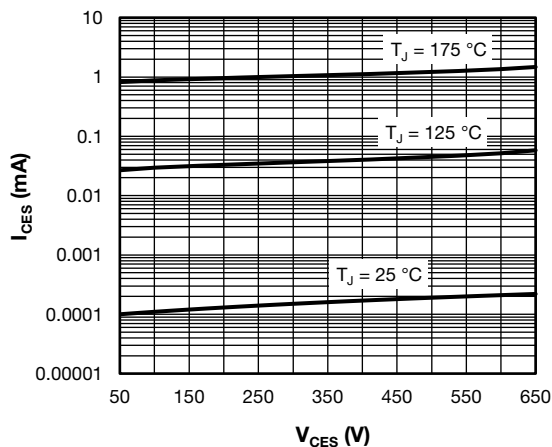


Fig. 6 - I_{CES} vs V_{CES}
Typical Q1 - Q4 Trench IGBT Zero Gate Voltage Collector Current

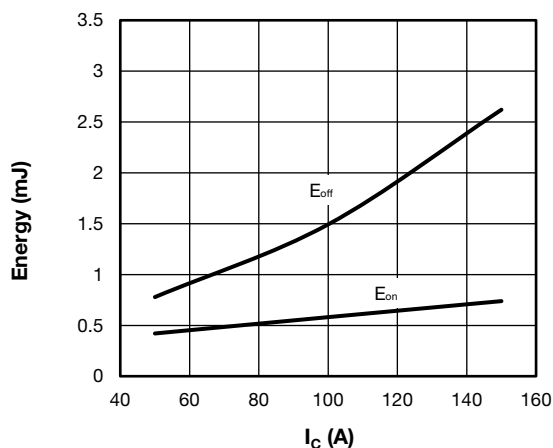


Fig. 7 - Energy Loss vs. I_C
(Typical Q1 - Q4 Trench IGBT Energy Loss vs. I_C (with D5 - D6 Clamping Diode)), $T_J = 125^\circ\text{C}$, $V_{CC} = 325\text{ V}$, $R_g = 4.7\ \Omega$, $V_{GE} = \pm 15\text{ V}$, $L = 500\ \mu\text{H}$

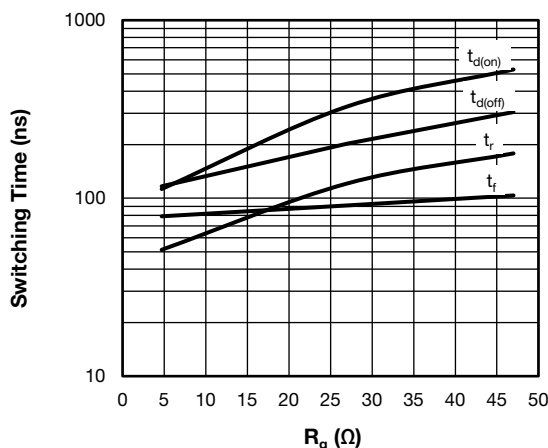


Fig. 10 - Switching Time vs. R_g
(Typical Q1 - Q4 Trench IGBT Switching Time vs. R_g (with D5 - D6 Clamping Diode)), $T_J = 125^\circ\text{C}$, $V_{CC} = 325\text{ V}$, $I_C = 100\text{ A}$, $V_{GE} = \pm 15\text{ V}$, $L = 500\ \mu\text{H}$

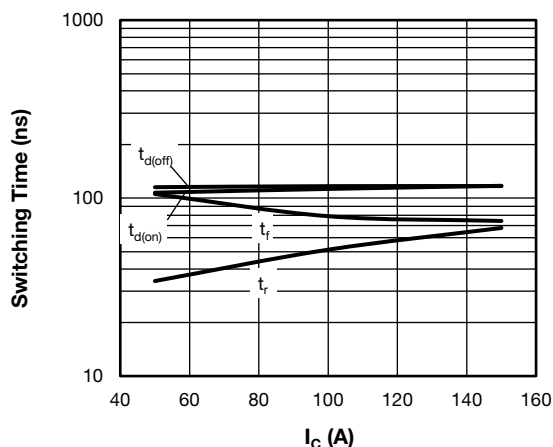


Fig. 8 - Switching Time vs. I_C
(Typical Q1 - Q4 Trench IGBT Switching Time vs. I_C (with D5 - D6 Clamping Diode)), $T_J = 125^\circ\text{C}$, $V_{CC} = 325\text{ V}$, $R_g = 4.7\ \Omega$, $V_{GE} = \pm 15\text{ V}$, $L = 500\ \mu\text{H}$

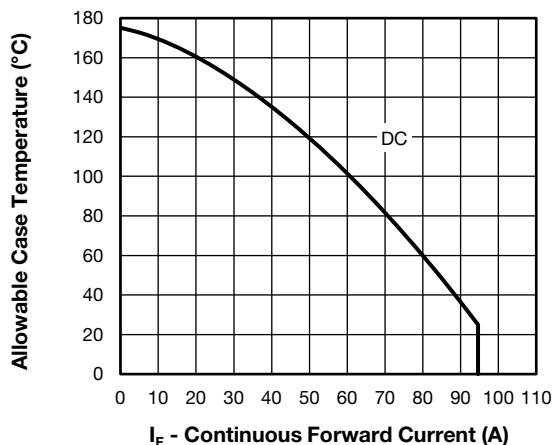


Fig. 11 - Allowable Case Temperature vs. Continuous Collector Current,
(Maximum D5 - D6 Diode Continuous Forward Current vs. Case Temperature)

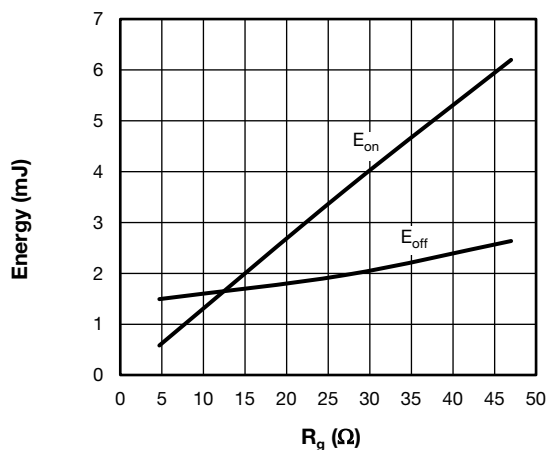


Fig. 9 - Energy Loss vs. R_g
(Typical Q1 - Q4 Trench IGBT Energy Loss vs. R_g (with D5 - D6 Clamping Diode)), $T_J = 125^\circ\text{C}$, $V_{CC} = 325\text{ V}$, $I_C = 100\text{ A}$, $V_{GE} = \pm 15\text{ V}$, $L = 500\ \mu\text{H}$

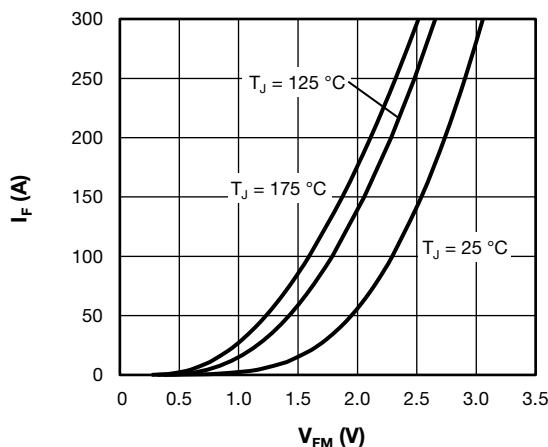


Fig. 12 - I_F vs. V_{FM}
(Typical D5 - D6 Clamping Diode Forward Characteristics)

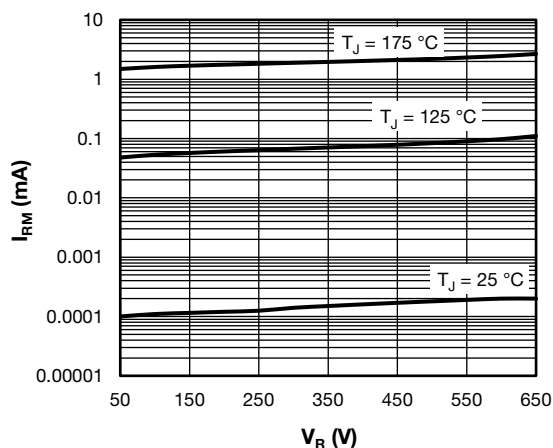


Fig. 13 - I_{RM} vs. V_R
(Typical D5 - D6 Clamping Diode Reverse Leakage Current)

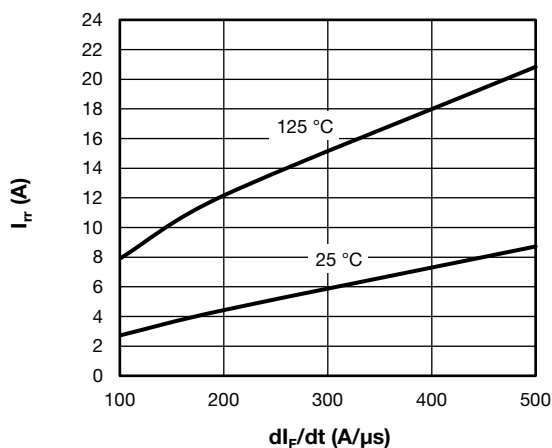


Fig. 15 - I_{rr} vs. di_F/dt
(Typical D5 - D6 Clamping Diode Reverse Recovery Current vs. di_F/dt , $V_{rr} = 200$ V, $I_F = 50$ A)

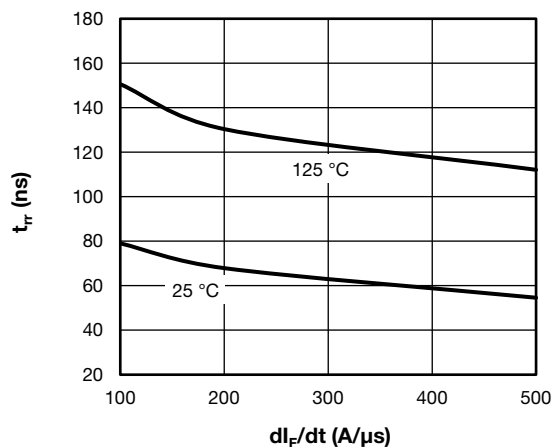


Fig. 14 - t_{rr} vs. di_F/dt
(Typical D5 - D6 Clamping Diode Reverse Recovery Time vs. di_F/dt , $V_{rr} = 200$ V, $I_F = 50$ A)

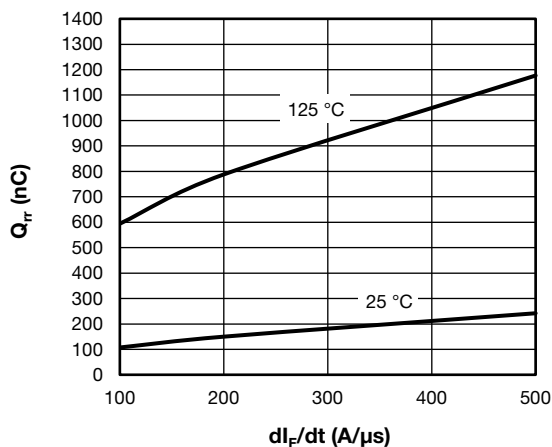


Fig. 16 - Q_{rr} vs. di_F/dt
(Typical D5 - D6 Clamping Diode Reverse Recovery Charge vs. di_F/dt , $V_{rr} = 200$ V, $I_F = 50$ A)

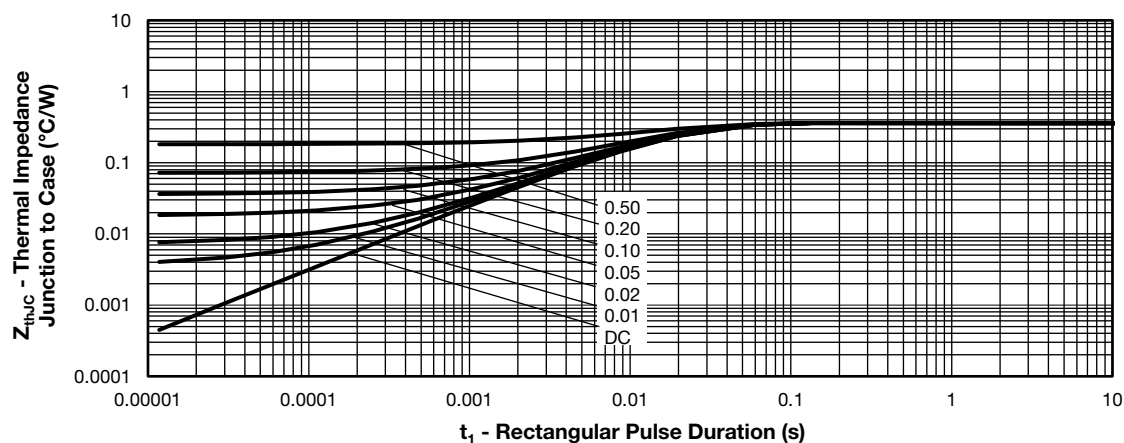


Fig. 17 - Z_{thJC} vs. t_1 Rectangular Pulse Duration (Maximum Thermal Impedance Z_{thJC} Characteristics - (Q1 - Q4 Trench IGBT))

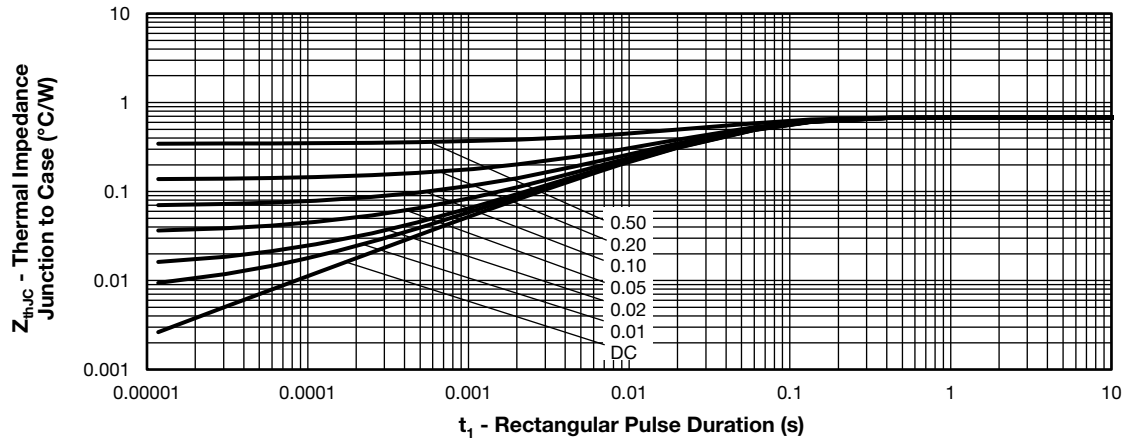


Fig. 18 - Z_{thJC} vs. t_1 Rectangular Pulse Duration (Maximum Thermal Impedance Z_{thJC} Characteristics - (D5 - D6 Clamping Diode))

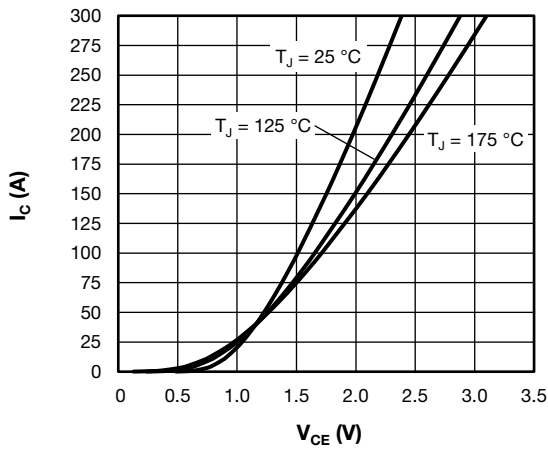


Fig. 19 - I_C vs. V_{CE}
(Typical Q2 - Q3 Trench IGBT Output Characteristics, $V_{GE} = 15$ V)

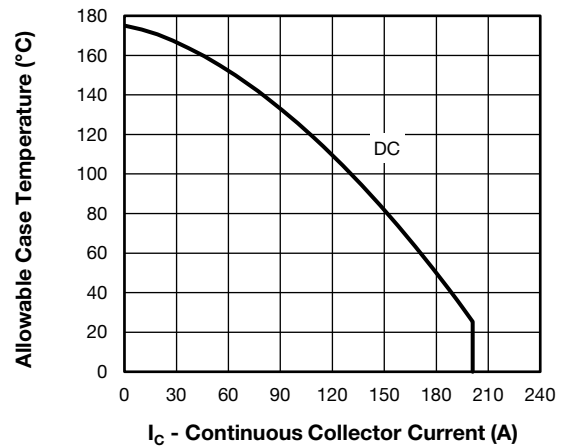


Fig. 21 - Allowable Case Temperature vs. Continuous Collector Current,
(Maximum Q2 - Q3 IGBT Continuous Collector Current vs. Case Temperature)

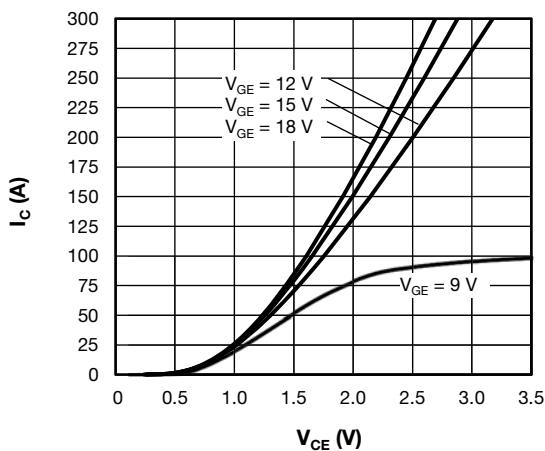


Fig. 20 - I_C vs. V_{CE} (Typical Q2 - Q3 Trench IGBT Output Characteristics, $T_J = 125^\circ\text{C}$)

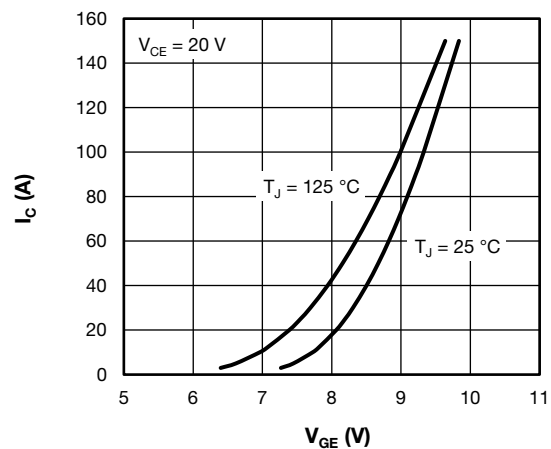


Fig. 22 - I_C vs. V_{GE}
(Typical Q2 - Q3 Trench IGBT Transfer Characteristics)

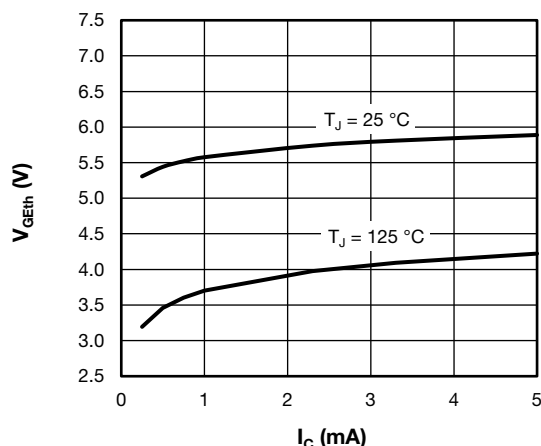


Fig. 23 - V_{GEth} vs. I_C
(Typical Q2 - Q3 Trench IGBT Gate Threshold Voltage)

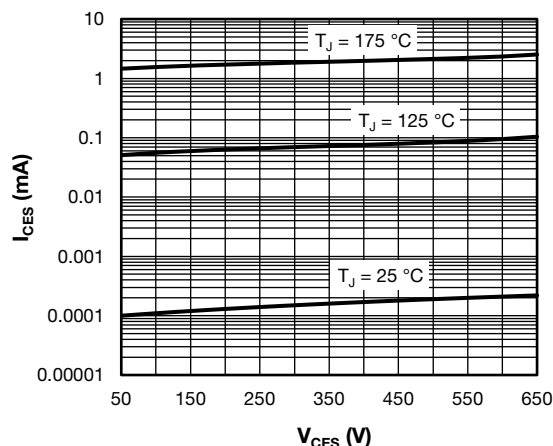


Fig. 24 - I_{CES} vs. V_{CES}
(Typical Q2 - Q3 Trench IGBT Zero Gate Voltage Collector Current)

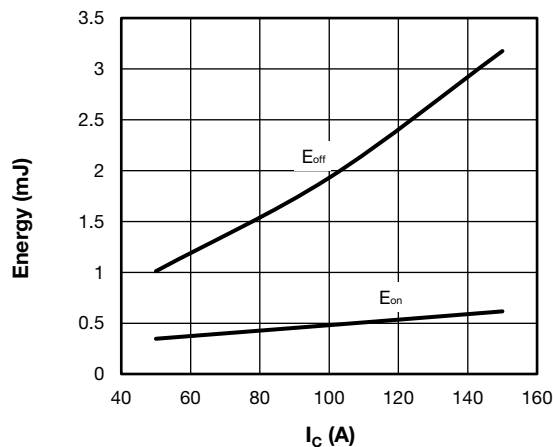


Fig. 25 - Energy Loss vs. I_C
(Typical Q2 - Q3 Trench IGBT Energy Loss vs. I_C (with D2 - D3 Antiparallel Diode)), $T_J = 125\text{ °C}$, $V_{CC} = 325\text{ V}$, $R_g = 4.7\text{ }\Omega$, $V_{GE} = \pm 15\text{ V}$, $L = 500\text{ }\mu\text{H}$

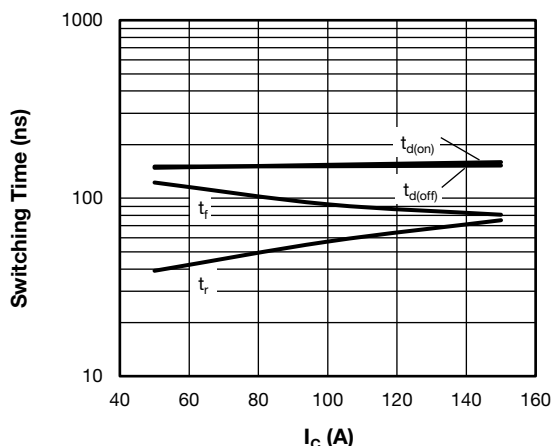


Fig. 26 - Switching Time vs. I_C
(Typical Q2 - Q3 Trench IGBT Switching Time vs. I_C (with D2 - D3 Antiparallel Diode)), $T_J = 125\text{ °C}$, $V_{CC} = 325\text{ V}$, $R_g = 4.7\text{ }\Omega$, $V_{GE} = \pm 15\text{ V}$, $L = 500\text{ }\mu\text{H}$

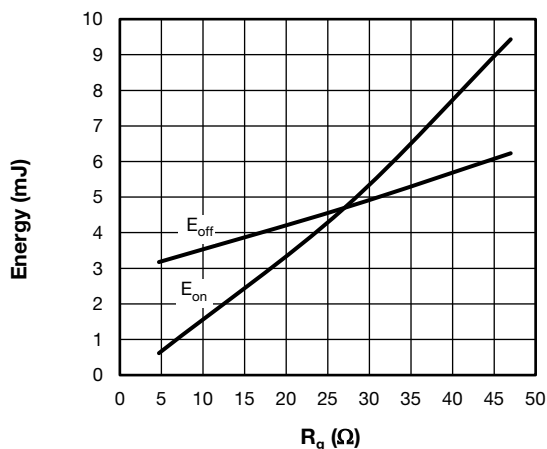


Fig. 27 - Energy Loss vs. R_g
(Typical Q2 - Q3 Trench IGBT Energy Loss vs. R_g (with D2 - D3 Antiparallel Diode)), $T_J = 125\text{ °C}$, $V_{CC} = 325\text{ V}$, $I_C = 150\text{ A}$, $V_{GE} = \pm 15\text{ V}$, $L = 500\text{ }\mu\text{H}$

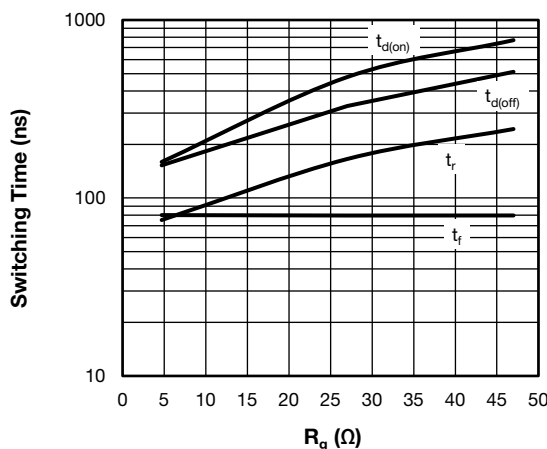


Fig. 28 - Switching Time vs. R_g (Typical Q2 - Q3 Trench IGBT Switching Time vs. R_g (with D2 - D3 Antiparallel Diode)), $T_J = 125\text{ °C}$, $V_{CC} = 325\text{ V}$, $I_C = 150\text{ A}$, $V_{GE} = \pm 15\text{ V}$, $L = 500\text{ }\mu\text{H}$

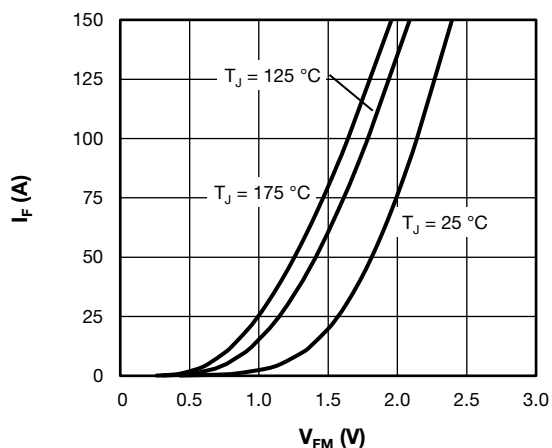


Fig. 29 - I_F vs. V_{FM}
(Typical D1 - D2 - D3 - D4 Antiparallel Diode Forward Characteristics)

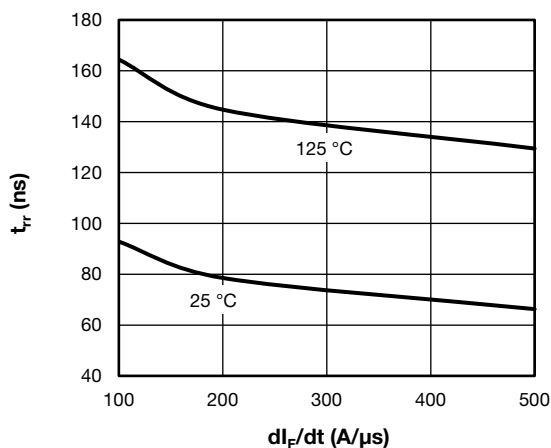


Fig. 31 - t_{rr} vs. dI_F/dt
(Typical D1 - D2 - D3 - D4 Antiparallel Diode Reverse Recovery Time vs. dI_F/dt , $V_{rr} = 200\text{ V}$, $I_F = 50\text{ A}$)

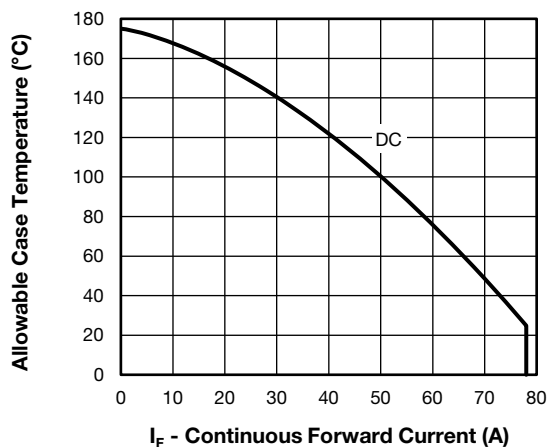


Fig. 30 - Allowable Case Temperature vs. Continuous Collector Current,
(Maximum D1- D2 - D3 - D4 Diode Continuous Forward Current vs. Case Temperature)

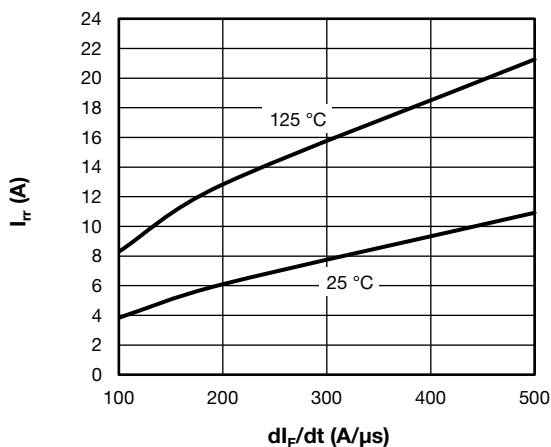


Fig. 32 - I_{rr} vs. dI_F/dt
(Typical D1 - D2 - D3 - D4 Antiparallel Diode Reverse Recovery Current vs. dI_F/dt , $V_{rr} = 200\text{ V}$, $I_F = 50\text{ A}$)

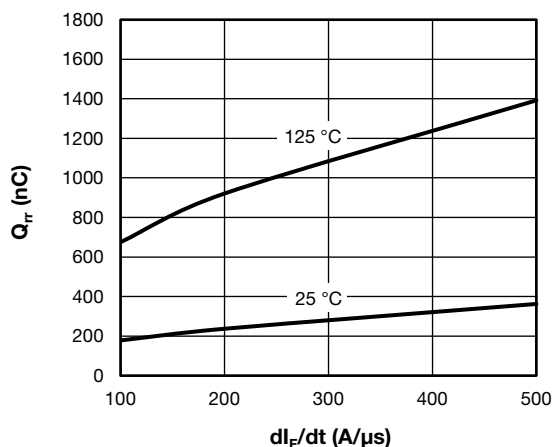


Fig. 33 - Q_{rr} vs. dI_F/dt
(Typical D1 - D2 - D3 - D4 Antiparallel Diode Reverse Recovery Charge vs. dI_F/dt , $V_{rr} = 200\text{ V}$, $I_F = 50\text{ A}$)

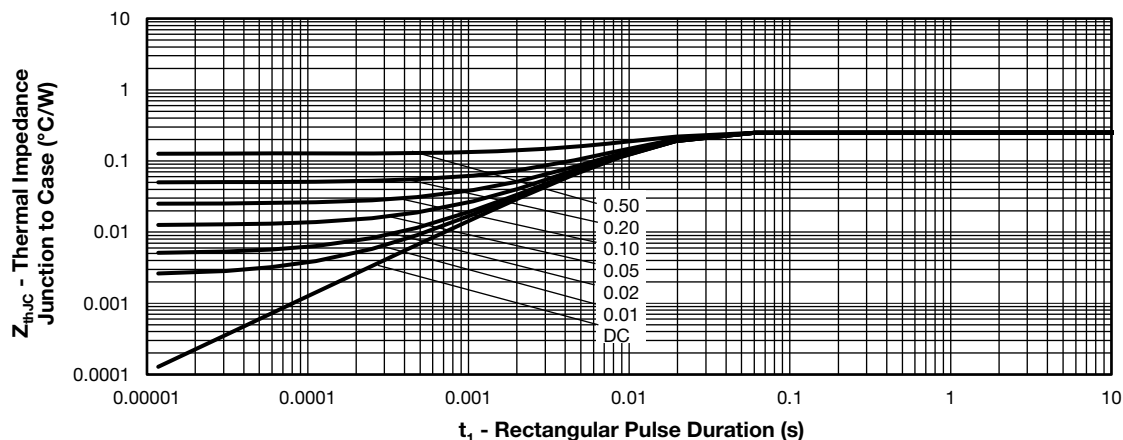


Fig. 34 - Z_{thJC} vs. t_1 Rectangular Pulse Duration (Maximum Thermal Impedance Z_{thJC} Characteristics - (Q2 - Q3 Trench IGBT))

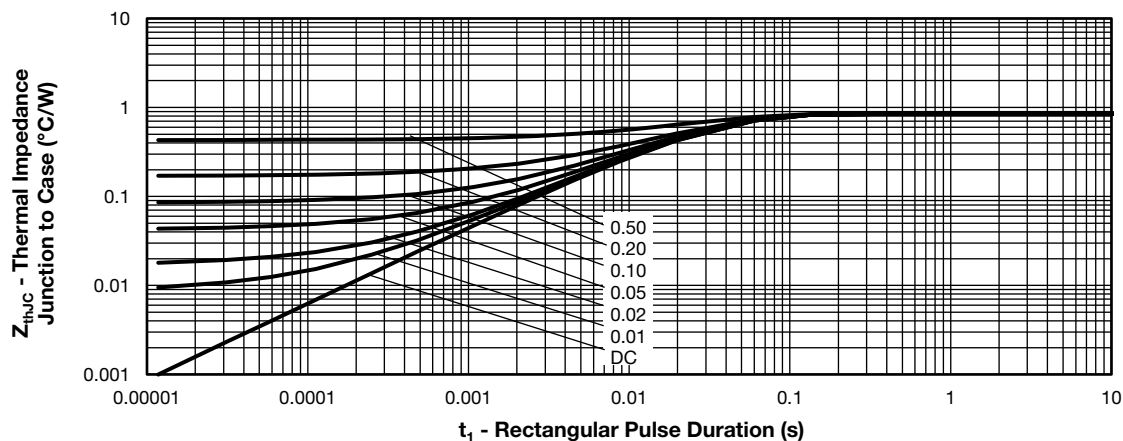
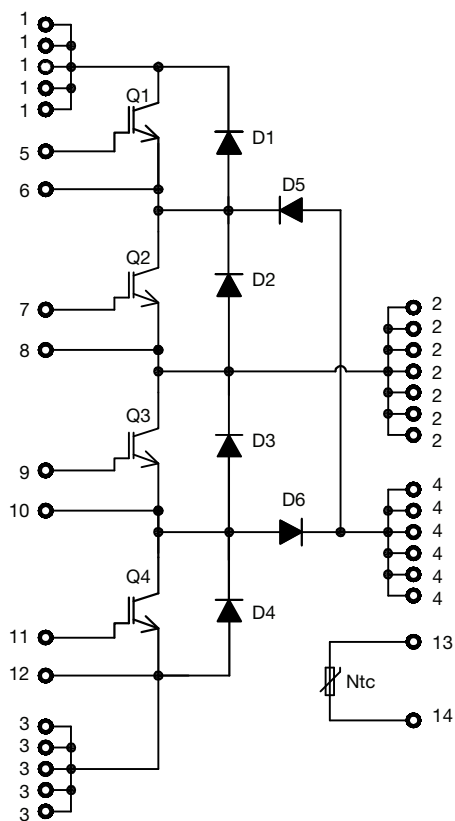


Fig. 35 - Z_{thJC} vs. t_1 Rectangular Pulse Duration (Maximum Thermal Impedance Z_{thJC} Characteristics - (D1 - D2 - D3 - D4 Antiparallel Diode))

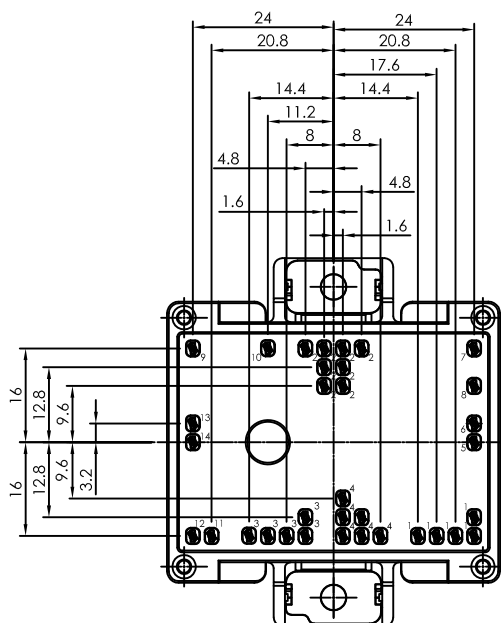
ORDERING INFORMATION TABLE

Device code	VS-	ET	F	150	Y	65	U
	①	②	③	④	⑤	⑥	⑦
①	-	Vishay Semiconductors product					
②	-	Package indicator (ET = EMIPAK-2B)					
③	-	Circuit configuration (F = 3-levels half-bridge inverter stage)					
④	-	Current rating (150 = 150 A)					
⑤	-	Switch die technology (Y = trench IGBT)					
⑥	-	Voltage rating (65 = 650 V)					
⑦	-	Diode die technology (U = ultrafast diode)					

CIRCUIT CONFIGURATION



PACKAGE in millimeters

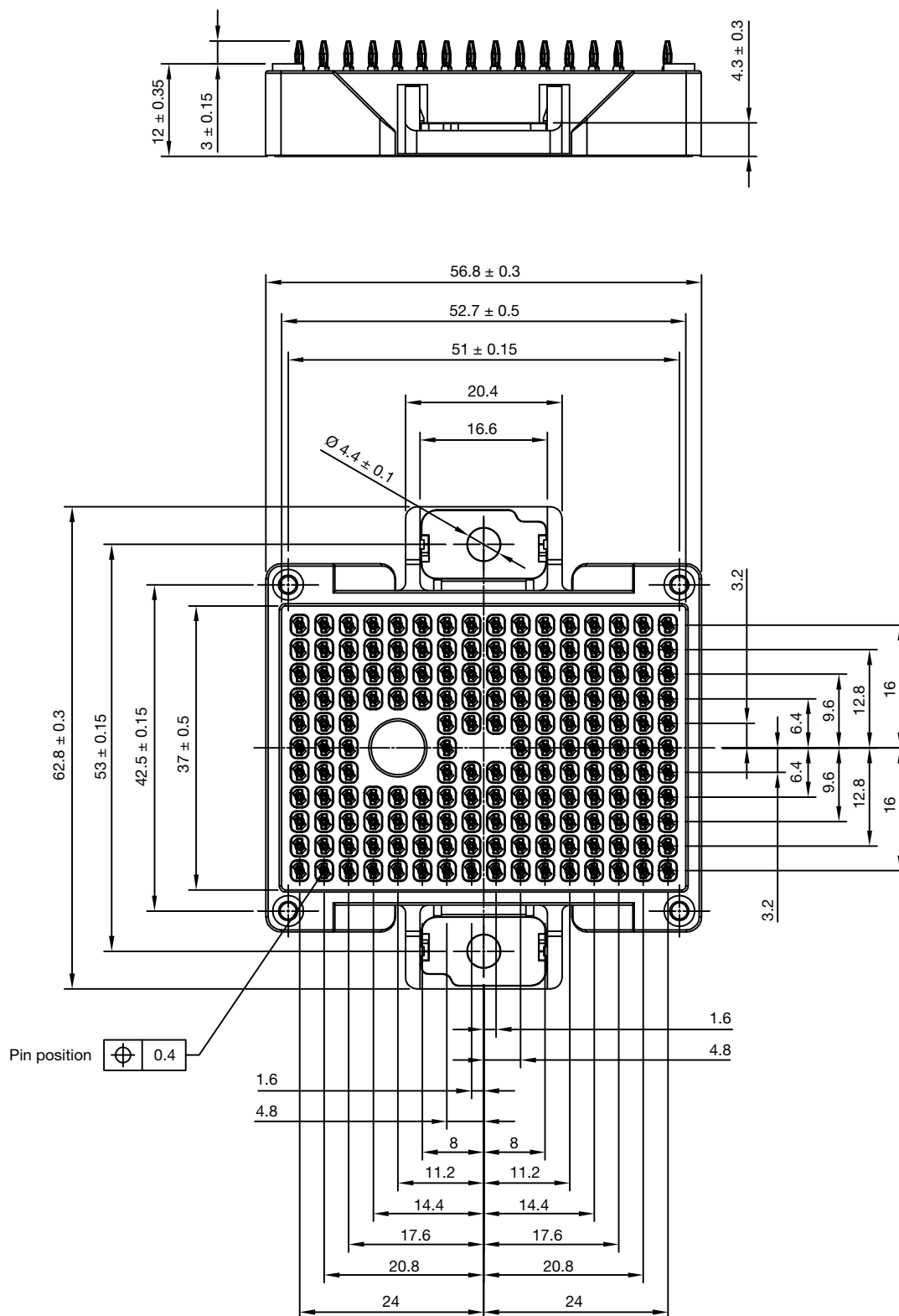


LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95559



EMIPAK-2B PressFit

DIMENSIONS in millimeters





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Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.